



Material Composition Sheet

Product: GS9010ACTCE3
 Package Type: SOIC-16W taped (1000/reel)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		8.02	Al	0.05	0.62	6234
			Si	7.97	99.37	993766
			Sub-total:	8.02	99.99	1000000
Die Attach	CRM1076R	2.33	Ag	1.75	75.10	751073
			Epoxy Resin	0.58	24.89	248927
			Sub-total:	2.33	99.99	1000000
Lead Finish External		1.33	Sn	1.33	100.00	1000000
			Sub-total:	1.33	100.00	1000000
Lead Finish Internal		0.27	Ag	0.27	100.00	1000000
			Sub-total:	0.27	100.00	1000000
Leadframe	Olin 195FH	120.51	Cu	117.50	97.50	975023
			Fe	2.83	2.34	23484
			P	0.04	0.03	332
			Zn	0.14	0.11	1162
			Sub-total:	120.51	99.98	1000001
Marking Ink	Wieder W238	0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G600	324.88	Carbon Black	0.97	0.29	2986
			Epoxy Cresol Novolac	13.00	4.00	40015
			Epoxy Resin	18.52	5.70	57006
			Phenol Resin	16.24	4.99	49988
			SiO2	276.15	85.00	850006
			Sub-total:	324.88	99.98	1000001
Wires	SGA3	0.78	Au	0.78	100.00	1000000
			Sub-total:	0.78	100.00	1000000
Total:		458.13				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5
 Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

www.gennum.com

The information contained in this document describes the homogeneous material composition of this product according to the definition set forth in the EU RoHS Directive 2002/95/EC. This information may have been derived from calculations based on information obtained from our suppliers. Gennum Corporation assumes no liability for any errors or omissions in this document. Gennum reserves the right to make changes to this document at any time without notice.